# 5V, Dual 4A/Dual-Phase 8A Step-Down DC/DC Regulator in 2.2mm × 2.7mm WLCSP

## FEATURES

- **Dual 4A Outputs**
- **Configurable as Single Output, 2-Phase 8A Buck**
- **High Efficiency: 12mΩ High-Side and 8mΩ Low-Side**
- **±1% Maximum Total DC Output Error**
- **Wide Bandwidth, Fast Transient Response**
- $V_{IN}$ Range: 2.25V to 5.5V
- $V_{OUT}$ Range: 0.5V to $V_{IN}$
- Programmable Frequency to 3MHz
- Low Ripple Burst Mode® Operation with Low $I_Q$
- Shutdown Current: 1.4µA
- 35ns Minimum On-Time
- Internal Compensation
- Precision Enable, Power Good for Power Sequencing
- Tiny 30-Lead, 2.2mm × 2.7mm WLCSP Package

## APPLICATIONS

- Servers, Telecom Power Supplies, Optical Networking
- Distributed DC Power Systems (POL)
- FPGA, ASIC, µP Core Supplies
- Industrial/Automotive/Communications

## DESCRIPTION

The LTC®3314A features dual monolithic synchronous 4A step-down converters in a 2.2mm × 2.7mm package for space saving applications with demanding performance requirements. Using a constant frequency, peak current mode architecture at switching frequencies up to 3MHz, both bucks achieve high efficiency and fast transient response with small external components. The LTC3314A can also be configured as a single output, 2-phase 8A step-down converter.

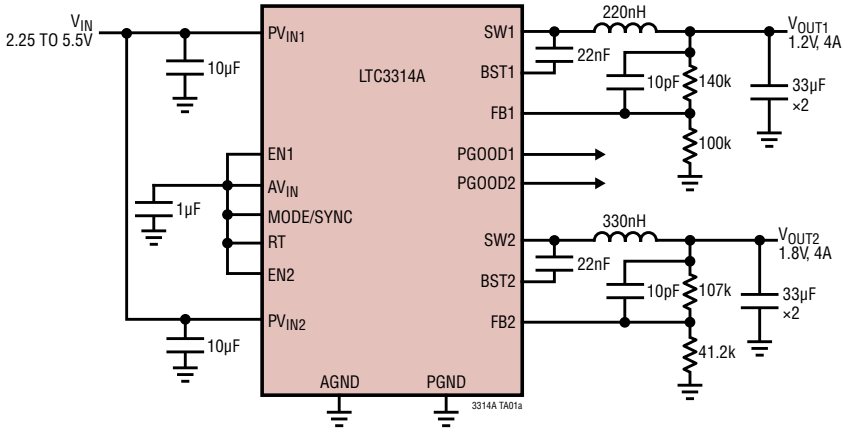
The LTC3314A operates in forced continuous or pulse-skipping mode for low noise, or in Burst Mode operation for high efficiency at light loads. The common switching frequency is set to a default 2MHz, programmed with an external resistor, or synchronized to an external oscillator via the MODE/SYNC pin. To reduce input ripple current, the dual converters switch 180 degrees out of phase.

With an input range of 2.25V to 5.5V the LTC3314A regulates to outputs as low as 500mV. Other features include precision enable thresholds, PGOOD signals, output overvoltage protection, thermal shutdown, and output short-circuit protection. The device is available in a 30-lead, 2.2mm × 2.7mm WLCSP package.

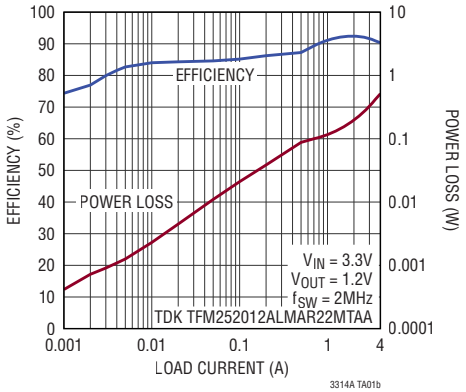


## TYPICAL APPLICATION

**Dual 2MHz 4A Buck Regulators**




**Efficiency and Power Loss in Burst Mode Operation**



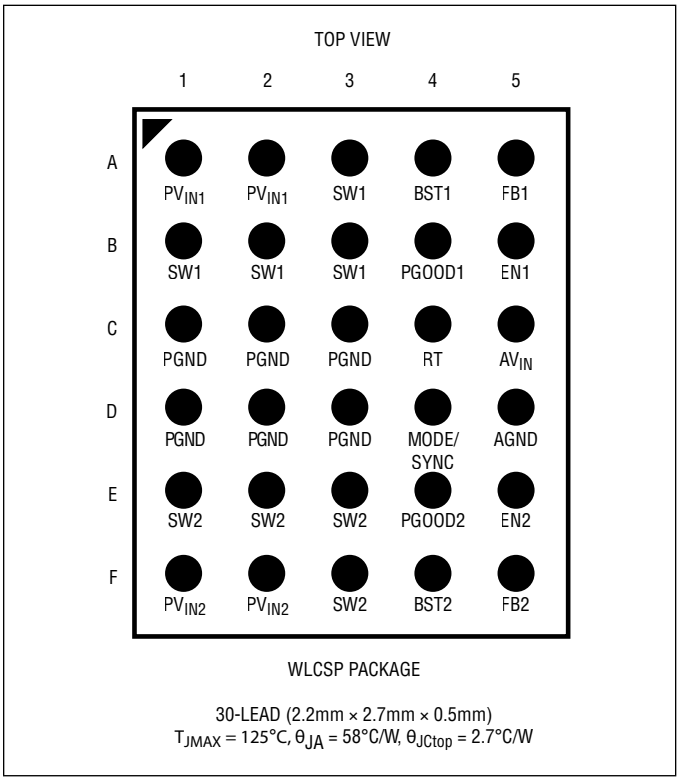

Rev. 0

## ABSOLUTE MAXIMUM RATINGS

**(Note 1)**

$PV_{IN1}$, $PV_{IN2}$, $AV_{IN}$ ..... –0.3V to 6V
EN1, EN2 ..... –0.3V to Lesser of ($AV_{IN}$ + 0.3V) or 6V
FB1, FB2 ..... –0.3V to Lesser of ($AV_{IN}$ + 0.3V) or 6V
MODE/SYNC ..... –0.3V to Lesser of ($AV_{IN}$ + 0.3V) or 6V
RT ..... –0.3V to Lesser of ($AV_{IN}$ + 0.3V) or 6V
BST1 to SW1 ..... –0.3V to 6V
BST2 to SW2 ..... –0.3V to 6V
AGND to PGND ..... –0.3V to +0.3V
PGOOD1, PGOOD2 ..... –0.3V to 6V
$I_{PGOOD1}$, $I_{PGOOD2}$ .....5mA
Operating Junction Temperature Range (Note 2)
LTC3314AA..... –40°C to 125°C
Storage Temperature Range ..... –65°C to 150°C
Maximum Reflow (Package Body)Temperature .... 260°C

## PIN CONFIGURATION




WLCSP PACKAGE

30-LEAD (2.2mm × 2.7mm × 0.5mm)
$T_{JMAX}$ = 125°C, $\theta_{JA}$ = 58°C/W, $\theta_{JCtop}$ = 2.7°C/W

## ORDER INFORMATION

| PART NUMBER | PART MARKING | FINISH CODE | PACKAGE TYPE | MSL RATING | TEMPERATURE RANGE |
|---|---|---|---|---|---|
| LTC3314AACBZ-R7 | 3314A | 01 | WLCSP (30-Lead Wafer Level Chip Scale Package) | 1 | –40°C to 125°C |

- Device temperature grade is indicated by a label on the shipping container.
- Pad or lead finish code is per IPC/JEDEC J-STD-609.

## ELECTRICAL CHARACTERISTICS

**The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A$ = 25°C. $V_{IN}$ = 3.3V, unless otherwise noted. $PV_{IN}$ = $PV_{IN1}$ = $PV_{IN2}$.**

| PARAMETER | CONDITIONS | | MIN | TYP | MAX | UNITS |
|---|---|---|---|---|---|---|
| Operating Supply Voltage ($PV_{IN}$) | | ● | 2.25 | | 5.5 | V |
| $PV_{IN}$ Undervoltage Lockout<br>$PV_{IN}$ Undervoltage Lockout Hysteresis | $PV_{IN}$ Rising | ● | 2.05 | 2.15<br>150 | 2.25 | V<br>mV |
| $PV_{IN}$ Quiescent Current in Shutdown | | | | 1.4 | 3 | µA |
| $PV_{IN}$ Quiescent Current with One Buck Enabled | Burst Mode Operation, Sleeping<br>All Modes, Not Sleeping, (Note 3) | | | 50<br>1.5 | 80<br>2.3 | µA<br>mA |
| $PV_{IN}$ Quiescent Current with Both Bucks Enabled | Burst Mode Operation, Sleeping<br>All Modes, Not Sleeping, (Note 3) | | | 90<br>2.8 | 130<br>4.2 | µA<br>mA |
| Enable Threshold<br>Enable Threshold Hysteresis | $V_{EN}$ Rising | ● | 0.375 | 0.4<br>50 | 0.425 | V<br>mV |
| EN Pin Leakage | | | | | ±20 | nA |
| **Voltage Regulation, Buck 1 and Buck 2** | | | | | | |
| Regulated Feedback Voltage ($V_{FB}$) | | ● | 495 | 500 | 505 | mV |
| Feedback Voltage Line Regulation | 2.25V < $PV_{IN}$ < 5.5V | | | 0.02 | 0.1 | %/V |
| Feedback Pin Input Current | $V_{FB}$ = 500mV | | | | ±20 | nA |
| Top Switch Current Limit ($I_{PEAKMAX}$) | Current Out of SW, $V_{OUT}/V_{IN} \leq 0.2$ | | 5.8 | 6.4 | 7.0 | A |
| Bottom Switch Current Limit ($I_{VALLEYMAX}$) | Current Out of SW | | | 5.2 | | A |
| Bottom Switch Reverse Current Limit ($I_{LIMR}$) | Current into SW, Forced Continuous Mode | | 1.5 | 4.0 | 5.5 | A |
| Top Switch ON-Resistance | | | | 12 | | mΩ |
| Bottom Switch ON-Resistance | | | | 8 | | mΩ |
| SW Leakage Current | Shutdown, $V_{IN}$ = 5.5V | | | | ±1 | µA |
| Minimum On-Time | $V_{IN}$ = 5.5V | ● | | 35 | 50 | ns |
| Maximum Duty-Cycle | | ● | 98 | | | % |
| Overtemperature Shutdown (OT)<br>Overtemperature Shutdown Hysteresis | Temperature Rising (Note 4) | | | 165<br>5 | | °C<br>°C |
| **Power Good/Soft-Start** | | | | | | |
| PGOOD Rising Threshold<br>PGOOD Hysteresis | As a % of the Regulated $V_{OUT}$ | ●<br>● | 97<br>0.6 | 98<br>1.1 | 99<br>1.6 | %<br>% |
| Overvoltage Rising Threshold<br>Overvoltage Hysteresis | As a % of the Regulated $V_{OUT}$ | ●<br>● | 107<br>1 | 110<br>2.2 | 114<br>3.5 | %<br>% |
| PGOOD Delay | | | | 100 | | µs |
| PGOOD Pull-Down Resistance | $V_{PGOOD}$ = 0.1V | | | 10 | 20 | Ω |
| PGOOD Leakage Current | $V_{PGOOD}$ = 5.5V | | | | 20 | nA |
| Soft-Start Time | $V_{OUT}$ Rising from 0V to PGOOD Threshold | ● | 0.25 | 1 | 3 | ms |

## ELECTRICAL CHARACTERISTICS

**The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A$ = 25°C. $V_{IN}$ = 3.3V, unless otherwise noted. $PV_{IN}$ = $PV_{IN1}$ = $PV_{IN2}$.**

| PARAMETER | CONDITIONS | | MIN | TYP | MAX | UNITS |
|---|---|---|---|---|---|---|
| **OSCILLATOR and MODE/SYNC** | | | | | | |
| Default Oscillator Frequency | $R_T$ = $AV_{IN}$ | ● | 1.85 | 2 | 2.15 | MHz |
| Oscillator Frequency | $R_T$ = 34.8kΩ to AGND | ● | 1.9 | 2 | 2.1 | MHz |
| Frequency Range | | ● | 1 | | 3 | MHz |
| Minimum SYNC High or Low Pulse Width | $R_T$ Programming and Synchronization | ● | 40 | | | ns |
| SYNC Level High on MODE/SYNC<br>SYNC Level Low on MODE/SYNC | | ●<br>● | 1.2 | | <br>0.4 | V<br>V |
| MODE/SYNC No Clock Detect Time | | ● | | 10 | | µs |
| MODE/SYNC Pin Threshold | For Programming Pulse-Skipping Mode<br>For Programming Burst Mode Operation | ●<br>● | <br>$V_{IN}$ –0.1 | | 0.1 | V<br>V |

**Note 1:** Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

**Note 2:** The LTC3314A is tested under pulsed load conditions such that $T_J$ = $T_A$. Specifications over the –40°C to 125°C operating junction temperature range are assured by design, characterization, and correlation with statistical process controls. High junction temperatures degrade operating lifetimes; operating lifetime is derated for junction temperatures above 125°C. Note that the maximum ambient temperature consistent with these specifications is determined by specific operating conditions in conjunction with board layout, the rated package thermal impedance, and other environmental factors. The junction temperature ($T_J$ in °C) is calculated from ambient temperature ($T_A$ in °C) and power dissipation ($P_D$ in Watts) according to the formula: $T_J = T_A + (P_D \bullet \theta_{JA})$, where $\theta_{JA}$ (in °C/W) is the package thermal impedance. See the PCB Layout Considerations section for more details.

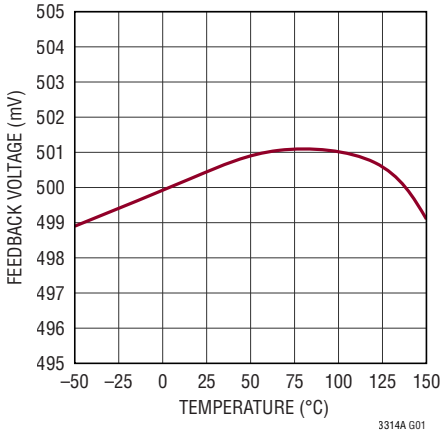
The LTC3314A includes overtemperature protection that protects the device during momentary overload conditions. Junction temperatures will exceed 150°C when overtemperature protection is engaged. Continuous operation above the specified maximum operating junction temperature may impair device reliability.

**Note 3:** Supply current specification does not include switching currents. Actual supply currents will be higher.

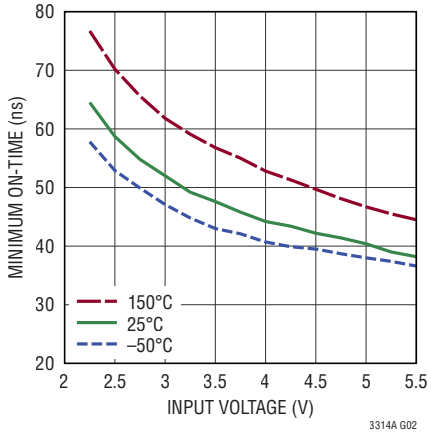
**Note 4:** Overtemperature shutdown is not tested in production.

## TYPICAL PERFORMANCE CHARACTERISTICS $T_A$ = 25°C, unless otherwise noted.

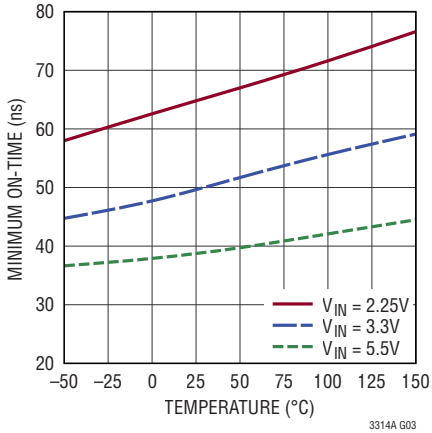
### Feedback Voltage



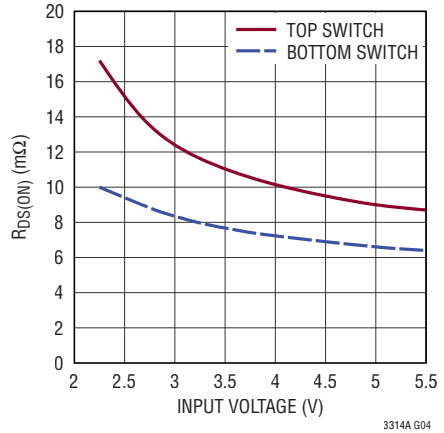

### Minimum On-Time vs $V_{IN}$



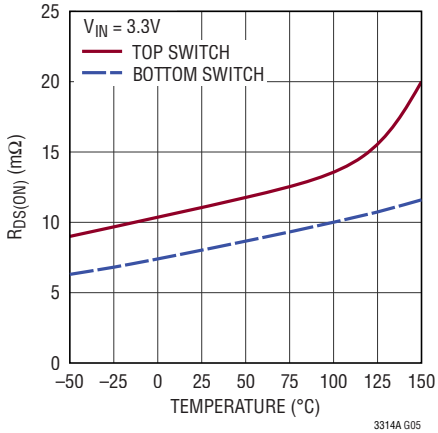

### Minimum On-Time vs Temperature



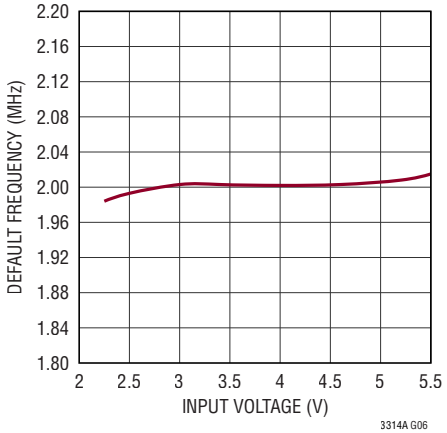

### Switch On-Resistance vs $V_{IN}$



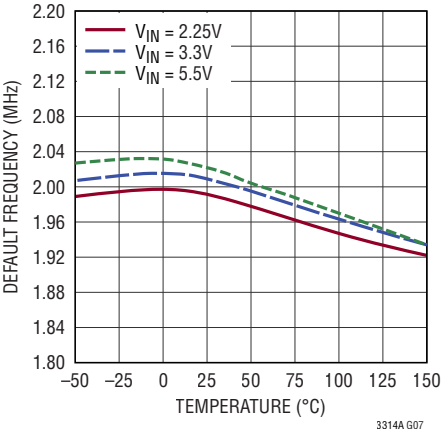

### Switch On-Resistance



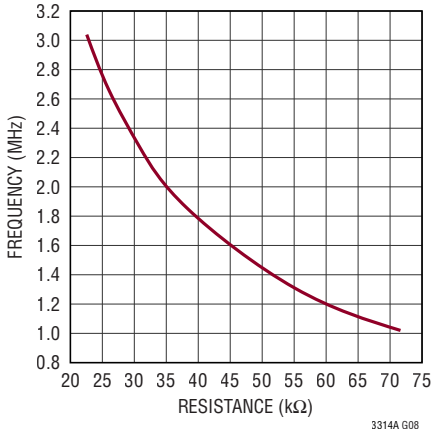

### Default Switching Frequency vs $V_{IN}$



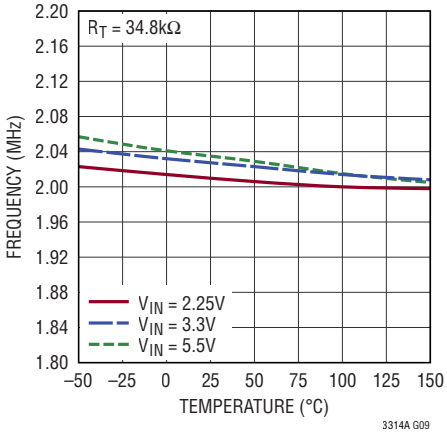

### Default Switching Frequency




### Switching Frequency vs $R_T$

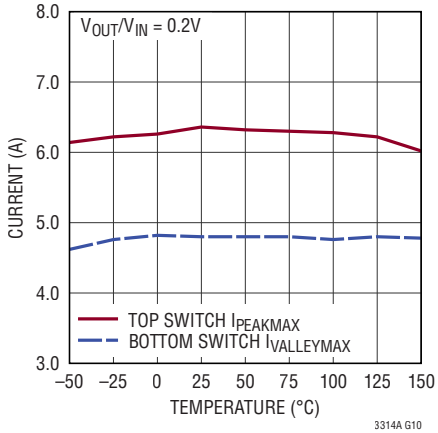



### Switching Frequency vs Temperature

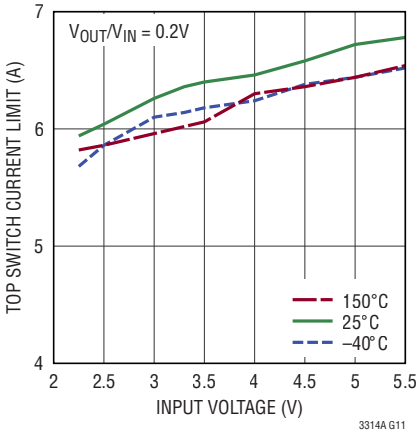


## TYPICAL PERFORMANCE CHARACTERISTICS $T_A$ = 25°C, unless otherwise noted.

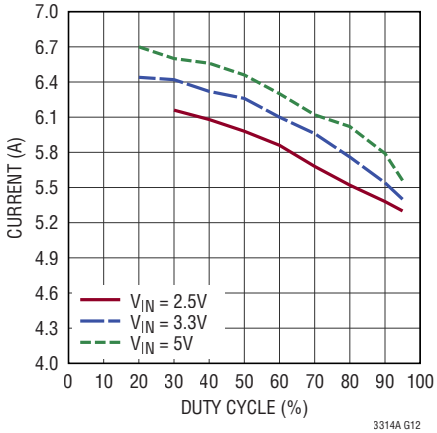
### Switch Current Limits



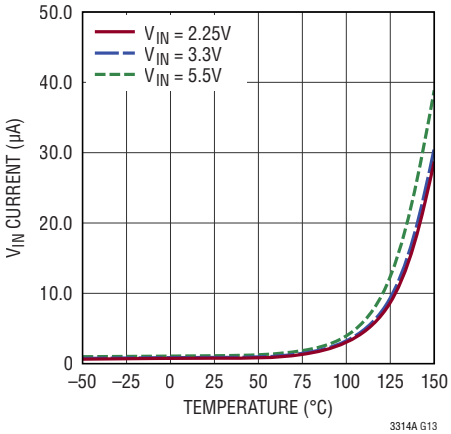

### Top Switch Current Limit vs $V_{IN}$



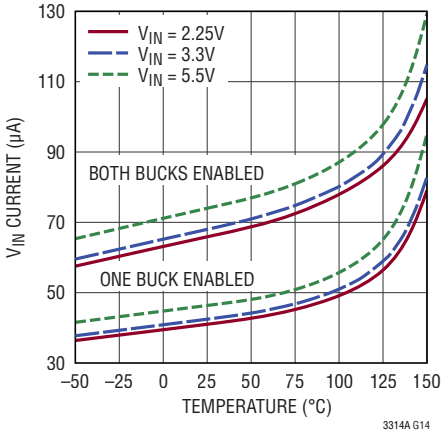

### Top Switch Current Limit



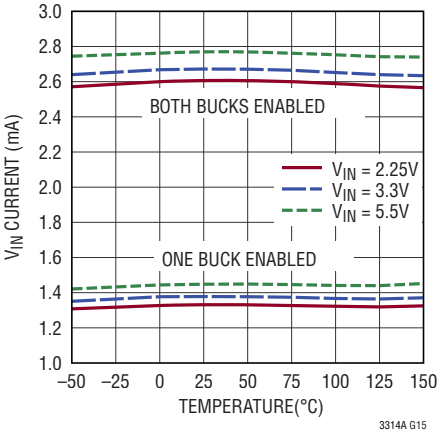

### $PV_{IN}$ Shutdown Current



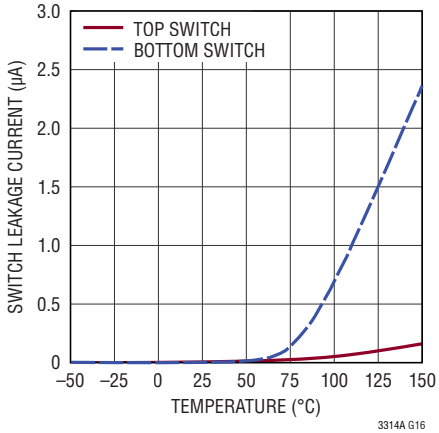

### $PV_{IN}$ Quiescent Current, Burst Mode Operation, Sleeping



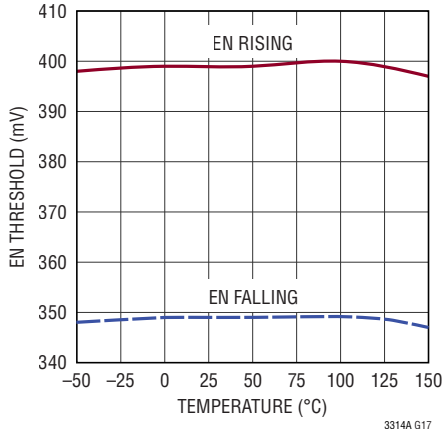

### $PV_{IN}$ Quiescent Current, All Modes, Not Sleeping



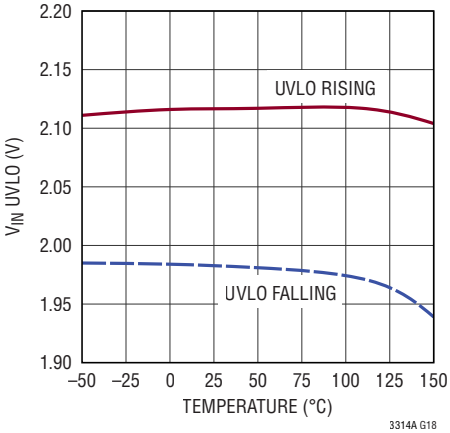

### Switch Leakage




### EN Threshold

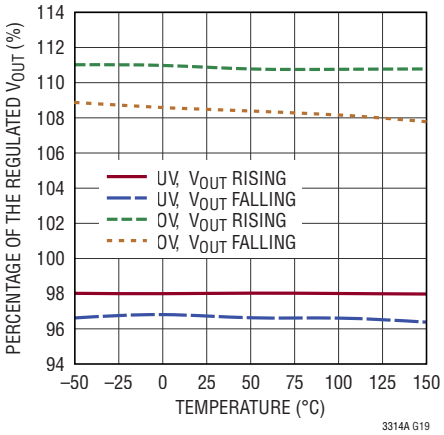



### $PV_{IN}$ UVLO Threshold

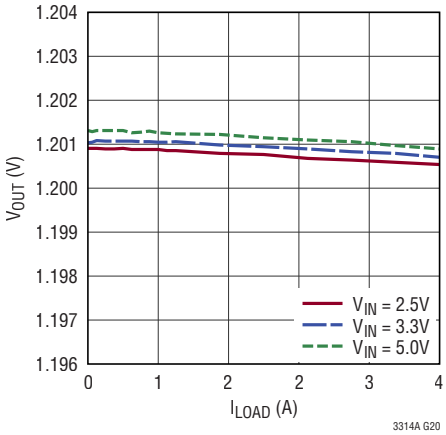


## TYPICAL PERFORMANCE CHARACTERISTICS $T_A$ = 25°C, unless otherwise noted.

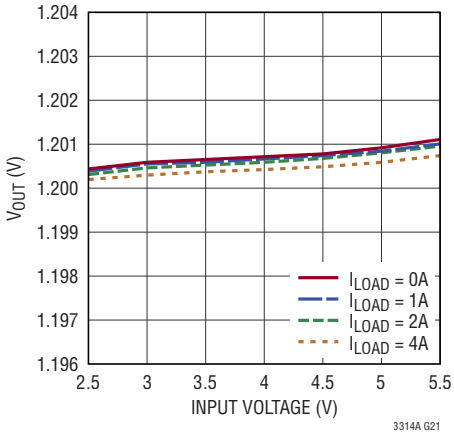
### UV, OV PGOOD Thresholds



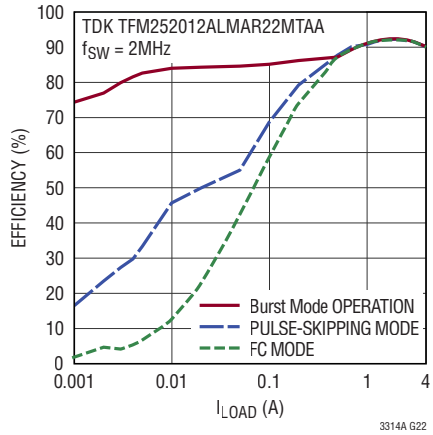

### VOUT Load Regulation in VOUT = 1.2V Application Forced Continuous Mode



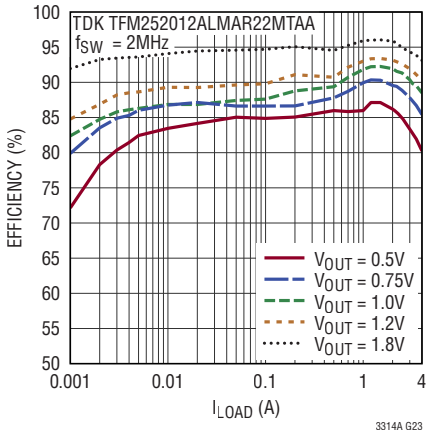

### VOUT Line Regulation



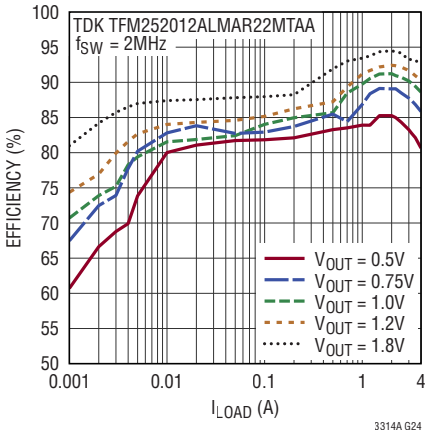

### Efficiency, VIN = 3.3V, VOUT = 1.2V, All Modes



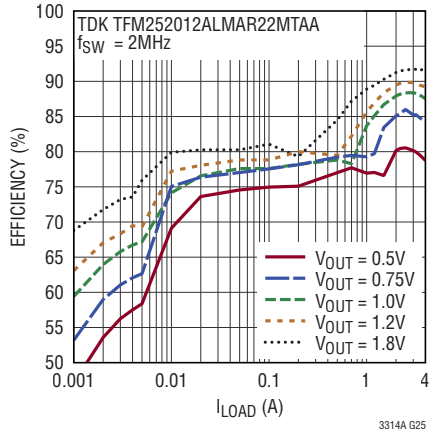

### Efficiency, VIN = 2.5V Burst Mode Operation



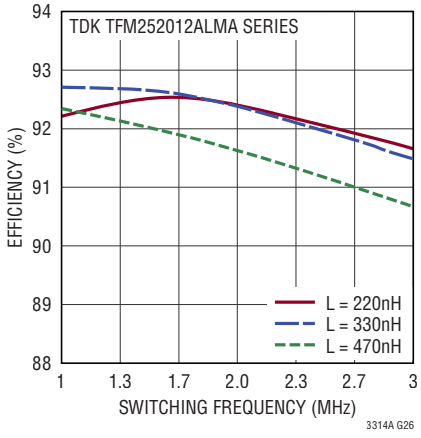

### Efficiency, VIN = 3.3V Burst Mode Operation



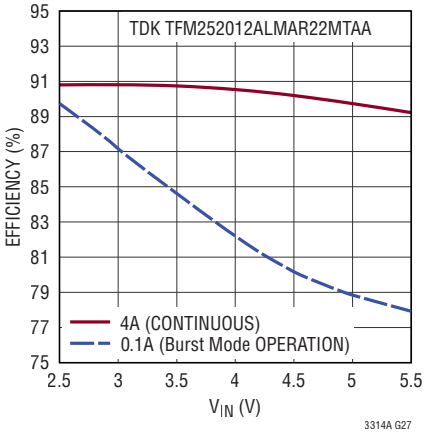

### Efficiency, VIN = 5.0V Burst Mode Operation




### Efficiency vs fSW 3.3V to 1.2V, ILOAD = 3A

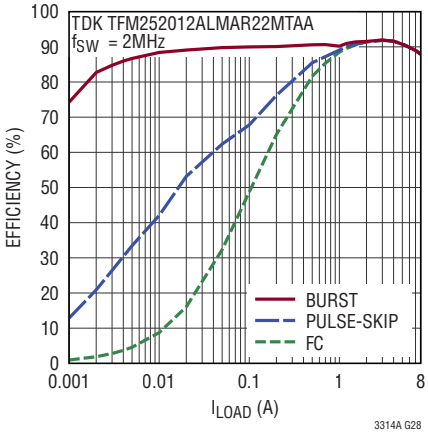



### Efficiency vs VIN VOUT = 1.2V, fSW = 2MHz

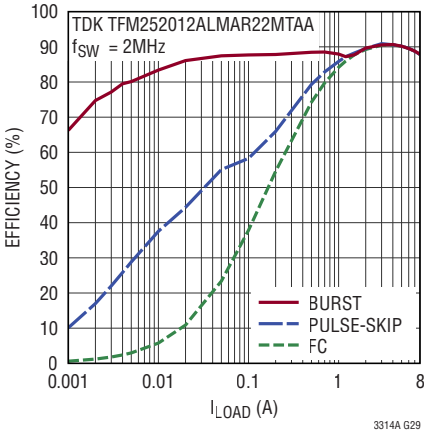


## TYPICAL PERFORMANCE CHARACTERISTICS $T_A$ = 25°C, unless otherwise noted.

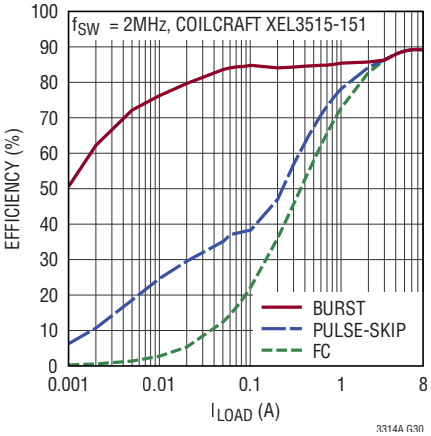
**2-Phase Efficiency vs Load, 2.5V to 1.0V**



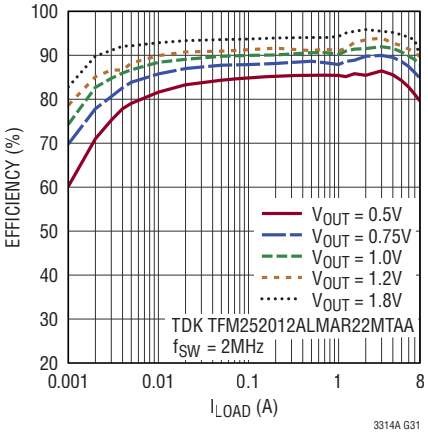

**2-Phase Efficiency vs Load, 3.3V to 1.0V**



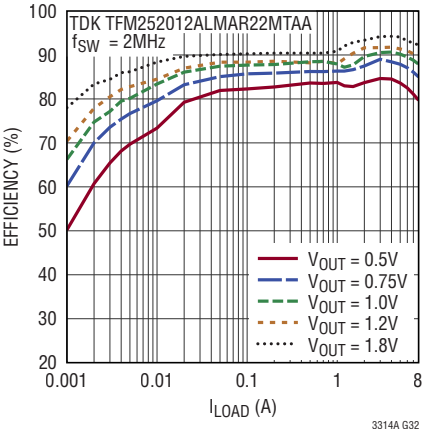

**2-Phase Efficiency vs Load, 5.0V to 1.0V**



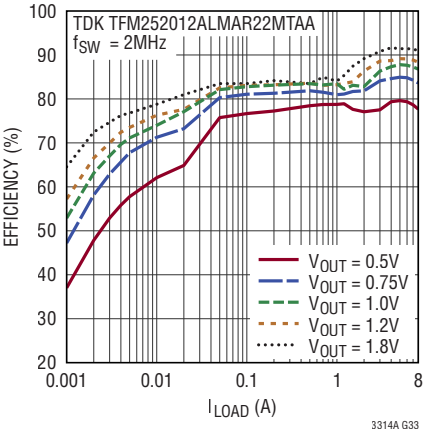

**2-Phase Efficiency, $V_{IN}$ = 2.5V Burst Mode Operation**




**2-Phase Efficiency, $V_{IN}$ = 3.3V Burst Mode Operation**

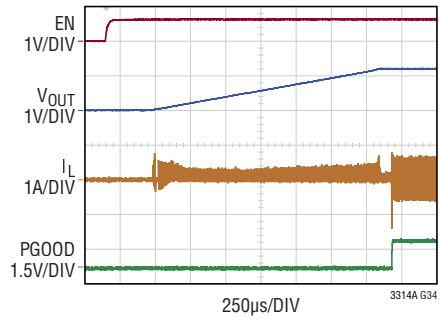



**2-Phase Efficiency, $V_{IN}$ = 5.0V Burst Mode Operation**



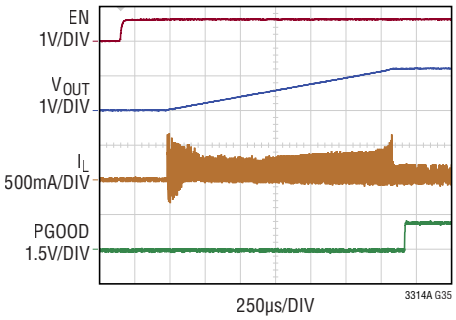
## TYPICAL PERFORMANCE CHARACTERISTICS $T_A$ = 25°C, unless otherwise noted.

### Start-Up Waveforms Forced Continuous Mode



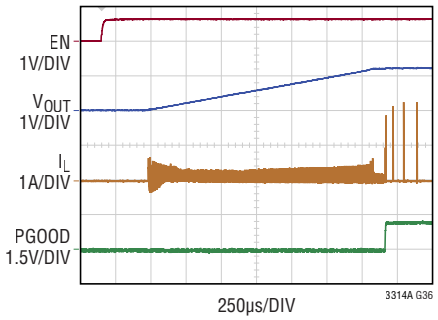

3.3V TO 1.2V, 2MHz TYPICAL APPLICATION
$R_{LOAD}$ = 120Ω

### Start-Up Waveforms Pulse-Skipping Mode



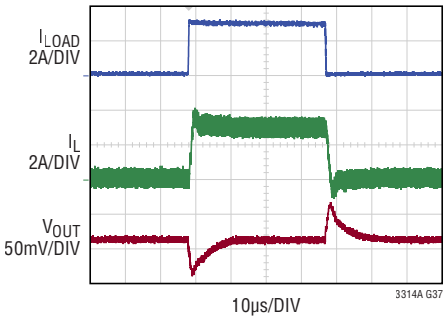

3.3V TO 1.2V, 2MHz TYPICAL APPLICATION
$R_{LOAD}$ = 120Ω

### Start-Up Waveforms Burst Mode Operation



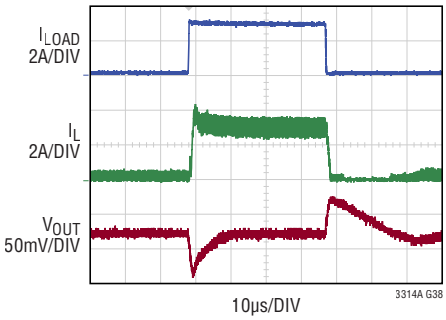

3.3V TO 1.2V, 2MHz TYPICAL APPLICATION
$R_{LOAD}$ = 120Ω

### Load Transient Response, Forced Continuous Mode



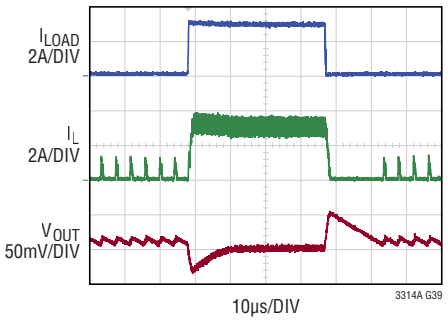

3.3V TO 1.2V, 2MHz TYPICAL APPLICATION
$C_{OUT}$ = 66µF, L = 220nH
LOAD STEP: 0.1A TO 3A IN 1µs

### Load Transient Response, Pulse-Skipping Mode



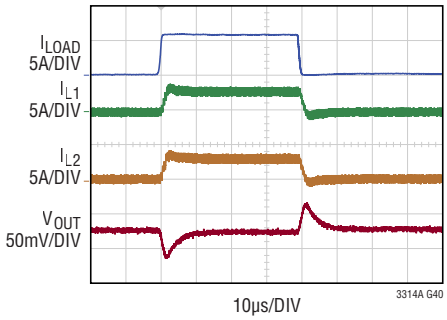

3.3V TO 1.2V, 2MHz TYPICAL APPLICATION
$C_{OUT}$ = 66µF, L = 220nH
LOAD STEP: 0.1A TO 3A IN 1µs

### Load Transient Response, Burst Mode Operation



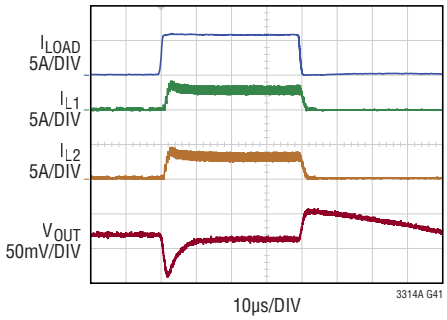

3.3V TO 1.2V, 2MHz TYPICAL APPLICATION
$C_{OUT}$ = 66µF, L = 220nH
LOAD STEP: 0.1A TO 3A IN 1µs

### 2-Phase Configuration Load Transient Response, Forced Continuous Mode



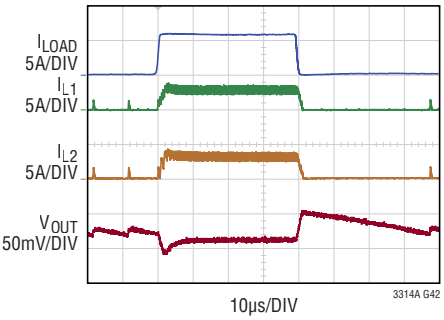

3.3V TO 1.0V, 2MHz 2-PHASE APPLICATION
$C_{OUT}$ = 158µF, L = 220nH
LOAD STEP: 0.1A TO 6A IN 1µs

### 2-Phase Configuration Load Transient Response, Pulse-Skipping Mode




3.3V TO 1.0V, 2MHz 2-PHASE APPLICATION
$C_{OUT}$ = 158µF, L = 220nH
LOAD STEP: 0.1A TO 6A IN 1µs

### 2-Phase Configuration Load Transient Response, Burst Mode Operation




3.3V TO 1.0V, 2MHz 2-PHASE APPLICATION
$C_{OUT}$ = 158µF, L = 220nH
LOAD STEP: 0.1A TO 6A IN 1µs

## PIN FUNCTIONS

**$PV_{IN1}$ (Leads A1, A2):** Input Supply for Buck Regulator 1. Supplies gate drive circuits and inductor current when the high side turns on. Bypass $PV_{IN1}$ to PGND with a separate low ESR capacitor close to the pins. $PV_{IN1}$ and $PV_{IN2}$ should be shorted externally. Use separate capacitors to PGND for $PV_{IN1}$ and $PV_{IN2}$ to prevent interaction between the buck regulators. There is an internal 20Ω resistor from $PV_{IN1}$ to $AV_{IN}$ to help create a filtered supply for the internal control circuits.

**SW1 (Leads A3, B1, B2, B3):** Switch Node for Buck Regulator 1. Connect an external inductor to this pin.

**BST1 (Lead A4):** Internal supply for high side gate drive circuits for Buck 1. Connect a 22nF capacitor from SW1 to BST1 close to the pins.

**FB1 (Lead A5):** Feedback Input for Buck Regulator 1. Program the output voltage of Buck 1 by connecting this pin to the middle node of a resistor divider between the output and ground. The FB1 pin is regulated to 500mV. A phase lead capacitor connected between $V_{OUT1}$ and FB1 may be used to optimize transient response.

**PGOOD1 (Lead B4):** Power Good (Open-Drain) Output for Buck Regulator 1. When the regulated output voltage is outside the power-good voltage window, and $PV_{IN}$ is above 2.25V, this pin is driven LOW. The PGOOD1 output is also pulled low when $PV_{IN}$ is above 2.25V and Buck Regulator 1 is in shutdown.

**EN1 (Lead B5):** Active High Enable Input for Buck Regulator 1. The EN1 pin has a precision threshold. An external resistor divider from $V_{IN}$, or from another supply, can be used to program when Buck Regulator 1 is enabled. If the enable function is not required, tie EN1 directly to $AV_{IN}$. The EN1 pin should not be floated.

**PGND (Leads C1, C2, C3, D1, D2, D3):** The PGND pins are the return path of the internal bottom side switches. Connect the PGND leads together. Connect the negative terminals of the input capacitors as close to the PGND pins as possible. The PGND node is the main thermal highway and should be connected to a large PCB ground plane with many large vias.

**RT (Lead C4):** The RT pin sets the switching frequency with an external resistor to AGND. If this pin is tied to $AV_{IN}$, the buck will switch at the default oscillator frequency. If an external clock is driving the MODE/SYNC pin, the RT pin is ignored.

**$AV_{IN}$ (Lead C5):** Filtered input supply used to bias the internal bandgap reference and buck control circuits. There are internal 20Ω resistors from $PV_{IN1}$ to $AV_{IN}$, and from $PV_{IN2}$ to $AV_{IN}$. Connect a 1µF ceramic capacitor from $AV_{IN}$ to AGND to provide a filtered supply for the internal control circuits. Do not externally load this pin.

**MODE/SYNC (Lead D4):** Mode Selection and External Clock Synchronization Input. Ground this pin to enable pulse-skipping mode. Tie this pin to $AV_{IN}$ to enable Burst Mode operation for higher efficiency at light loads. Float this pin to enable forced continuous mode for fast transient response and full frequency operation over a wide load range. Drive MODE/SYNC with an external clock to synchronize both switchers to the applied frequency. The slope compensation is automatically adapted to the external clock frequency. In the absence of an external clock, the RT pin controls the switching frequency.

**AGND (Lead D5):** The AGND pin is the ground pin for the internal bias circuits, including the bandgap reference. Connect the bottom resistor of the FB1 and FB2 resistor dividers to the AGND pin for accurate output voltage regulation.

**SW2 (Leads E1, E2, E3, F3):** Switch Node for Buck Regulator 2. Connect an external inductor to this pin.

**PGOOD2 (Lead E4):** Power Good (Open-Drain) Output for Buck Regulator 2. When the regulated output voltage is outside the power-good voltage window, and $PV_{IN}$ is above 2.25V, this pin is driven LOW. The PGOOD2 output is also pulled low when $PV_{IN}$ is above 2.25V and Buck Regulator 2 is in shutdown.

## PIN FUNCTIONS

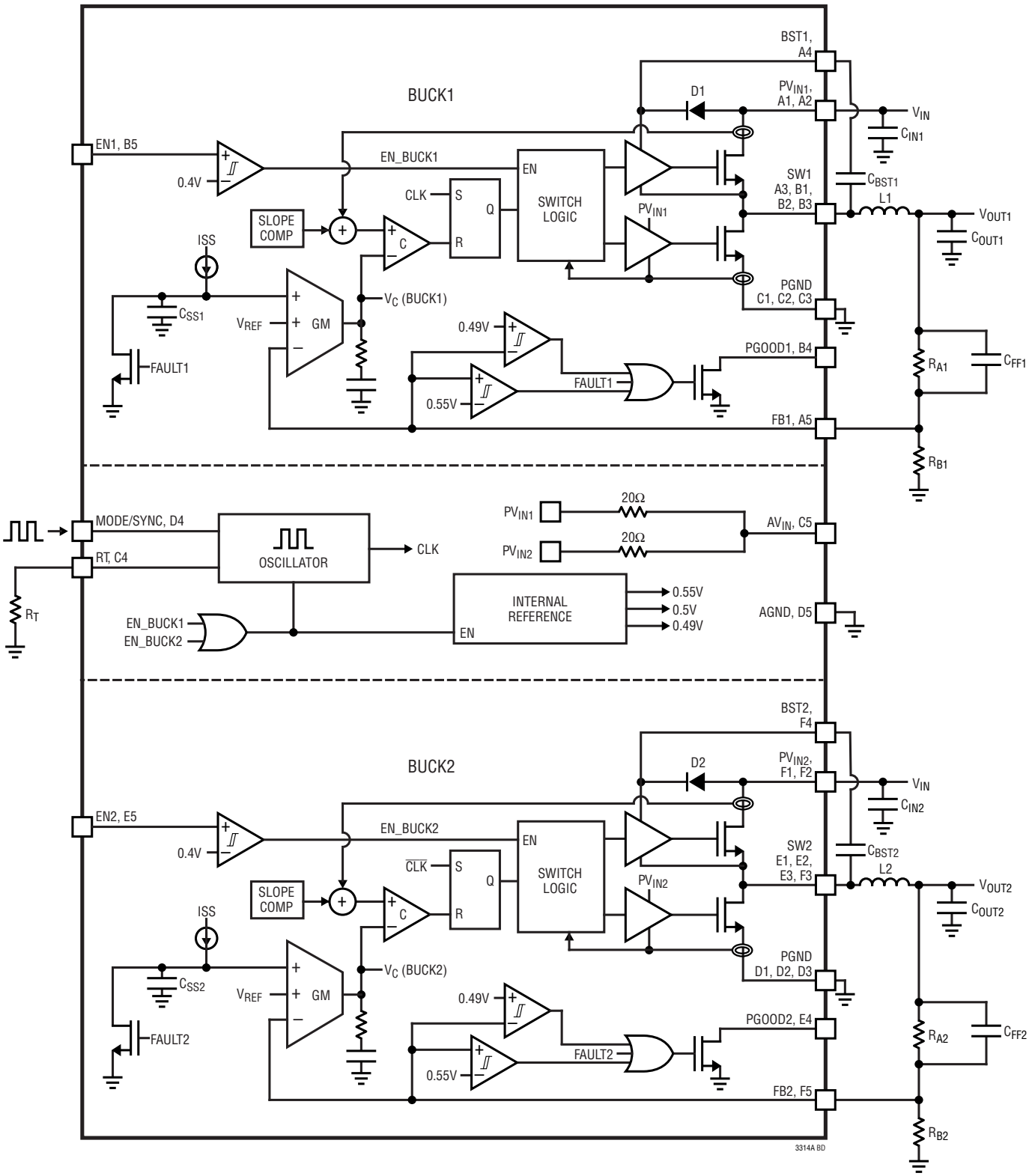
**EN2 (Lead E5):** Active High Enable Input for Buck Regulator 2. The EN2 pin has a precision threshold. An external resistor divider from $V_{IN}$, or from another supply, can be used to program when Buck Regulator 2 is enabled. If the enable function is not required, tie EN2 directly to $AV_{IN}$. The EN2 pin should not be floated.

**$PV_{IN2}$ (Leads F1, F2):** Input Supply for Buck Regulator 2. Supplies gate drive circuits and inductor current when the high side turns on. Bypass $PV_{IN2}$ to PGND with a separate low ESR capacitor close to the pins. $PV_{IN1}$ and $PV_{IN2}$ should be shorted externally. Use separate capacitors to PGND for $PV_{IN1}$ and $PV_{IN2}$ to prevent interaction between the buck regulators. There is an internal 20Ω resistor from $PV_{IN2}$ to $AV_{IN}$ to help create a filtered supply for the internal control circuits.

**BST2 (Lead F4):** Internal supply for high side gate drive circuits for Buck 2. Connect a 22nF capacitor from SW2 to BST2 close to the pins.

**FB2 (Lead F5):** Feedback Input for Buck Regulator 2. Program the output voltage of Buck 2 by connecting this pin to the middle node of a resistor divider between the output and ground. The FB2 pin is regulated to 500mV. A phase lead capacitor connected between $V_{OUT2}$ and FB2 may be used to optimize transient response. Connect FB2 to $AV_{IN}$ to program the part for single output, 2-phase operation.

## BLOCK DIAGRAM



# OPERATION

### Dual Buck Switching Regulators

The LTC3314A is a 5V dual 4A monolithic, constant frequency, peak current mode step-down DC/DC converter. The synchronous buck switching regulators are internally compensated and require only external feedback resistors to set the output voltage.

An internal oscillator, with frequency set using a resistor on the RT pin or synchronized to an external clock, turns on the internal top power switch at the start of each clock cycle, (the clock's rising edge for Buck 1). Current in the inductor then increases until the top switch current comparator trips and turns off the top power switch. The peak inductor current at which the top switch turns off is controlled by an internal $V_C$ voltage. The error amplifier regulates $V_C$ by comparing the voltage on the FB pin with an internal 500mV reference. When the load current increases it causes a reduction in the feedback voltage relative to the reference leading the error amplifier to raise the $V_C$ voltage until the average inductor current matches the new load current. When the top power switch turns off, the synchronous power switch turns on and ramps down the inductor current for the remainder of the clock cycle or, if in pulse-skipping or Burst Mode operation, until the inductor current falls to zero. If overload conditions result in excessive current flowing through the bottom switch, the next clock cycle will be skipped until switch current returns to a safe level. The top switches of the two buck regulators are turned on 180 degrees out of phase to reduce input current ripple.

Each buck switching regulator has its own SW, FB, PGOOD, and EN pins. The enable pins have precision 400mV thresholds which may be used to provide event-based power-up sequencing by connecting the enable pin to the output of another buck through a resistor divider. If the EN pin of a buck is low, that buck is in shutdown and in a low quiescent current state. If both EN pins are low, both bucks are in shutdown, the SW pins are high impedance, and the quiescent current of the LTC3314A is 1.4µA (typical). If either EN pin is above the enable threshold of 400mV, its respective buck is enabled.

Both buck regulators have forward and reverse-current limiting, short-circuit protection, output overvoltage protection, and soft-start to limit inrush current during start-up or recovery from a short-circuit.

### 2-Phase, Single Output Operation

The LTC3314A is easily configured as a single output, 2-phase, 8A buck regulator by connecting the FB2 pin to $AV_{IN}$, and connecting the EN2 pin to AGND. The PGOOD2 pin can be floated or shorted to ground. The EN1 pin will control the enable for both power stages, and the PGOOD1 pin functions as the power good indicator.

The part detects that FB2 is connected high and uses the output of the error amplifier ($V_C$) for Buck 1 to control the peak inductor current for both buck power stages. The top switches of the two phases are turned on 180 degrees out of phase to reduce input current ripple. The difference between peak inductor currents of the two phases are determined by internal matching and will typically be within 10% of each other at high currents.

The equations used to determine the inductor value for a single phase 4A buck are also used to select the inductors for the dual-phase 8A circuit (see the Applications Information section for inductor selection). The total capacitance on the 2-phase output should be double what is calculated for a single phase 4A buck (see the Applications Information section for output capacitor selection).

When waking up from sleep in Burst Mode operation, the top switches of the two phases are turned on initially without a delay, to improve the transient response coming out of sleep. The 180-degree phase difference will start on the subsequent turn-on after exiting sleep.

### Input Supply

The $AV_{IN}$ pin is a noise filtered version of $PV_{IN}$ used to bias the internal bandgap reference and buck control circuits. A 1µF external filter capacitor should be connected from $AV_{IN}$ to AGND, and no current should be drawn for external circuits. $AV_{IN}$ connects to the $PV_{IN1}$ and $PV_{IN2}$ pins through internal 20Ω filter resistors.

## OPERATION

$PV_{IN1}$ and $PV_{IN2}$ are not connected internally and should be externally shorted to a single input supply. Each $PV_{IN}$ pin should have its own input bypass capacitor to PGND.

### Mode Selection

The buck switching regulators operate in three different modes set by the MODE/SYNC pin: pulse-skipping mode (when the MODE/SYNC pin is set low), forced continuous mode (when the MODE/SYNC pin is floating), and Burst Mode operation (when the MODE/SYNC pin is set high). The MODE/SYNC pin sets the operating mode for both buck switching regulators.

In pulse-skipping mode, the oscillator operates continuously, and positive SW transitions are aligned to the clock. Negative inductor current is disallowed, and switch pulses are skipped for light loads to regulate the output voltage.

In forced continuous mode, the oscillator operates continuously. The top switch turns on every cycle and regulation is maintained by allowing the inductor current to reverse at light load. This mode allows the buck to run at a fixed frequency with minimal output ripple. In forced continuous mode, if the inductor current reaches 4A (typical) into the SW pin, the bottom switch will turn off for the remainder of the cycle to limit the current.

In Burst Mode operation at light loads, the output capacitor is charged to a voltage slightly higher than its regulation point. The regulator then goes into a sleep state, during which time the output capacitor provides the load current. In sleep, most of the regulator's circuitry is powered down, helping conserve input power. When the output voltage drops below its programmed value, the circuitry is powered on and another burst cycle begins. The sleep time decreases as load current increases. In Burst Mode operation, the regulator will burst at light loads whereas at higher loads it will operate in constant frequency PWM mode.

### Synchronizing the Oscillator to an External Clock

The LTC3314A's internal oscillator is synchronized through an internal PLL circuit to an external frequency by applying a square wave clock signal to the MODE/SYNC pin. During synchronization, the Buck 1 top power switch turn-on is locked to the rising edge of the external frequency source. The Buck 2 top switch turn-on will be 180 degrees out of phase with respect to Buck 1. While synchronizing, the buck switching regulators operate in forced continuous mode. The slope compensation is automatically adapted to the external clock frequency. The synchronization frequency range is 1MHz to 3MHz.

After detecting an external clock on the first rising edge of the MODE/SYNC pin, the internal PLL gradually adjusts its operating frequency to match the frequency and phase of the signal on the MODE/SYNC pin. When the external clock is removed, the LTC3314A will detect the absence of the external clock within approximately 10µs. During this time, the PLL will continue to provide clock cycles. Once the external clock removal has been detected, the oscillator will gradually adjust its operating frequency to the one programmed by the RT pin.

### Output Power Good

Both buck switching regulators have an external open-drain PGOOD pin, that operates independently of the other. When a buck output voltage is within the –2/+10% (typical) window of the nominal regulation voltage, the output is considered good. The corresponding open-drain PGOOD pin goes high impedance and is typically pulled high with an external resistor. Otherwise, an internal pull-down device will pull the corresponding PGOOD pin low. Each PGOOD pin is also pulled low during the following fault conditions: the corresponding buck EN pin is low, $V_{IN}$ is too low, or thermal shutdown. To filter noise and short duration output voltage transients, the lower thresholds have a hysteresis of 1.1% (typical), the upper thresholds have a hysteresis of 2.2% (typical), and transitions of the PGOOD pins have a built-in time delay, typically 100µs.

### Output Overvoltage Protection

If there is an output overvoltage event, which occurs when the FB pin voltage is greater than 110% of nominal, the buck regulator top power switch will be turned off. If the

## OPERATION

output remains out of regulation for more than 100µs, the PGOOD pin will be pulled low.

An output overvoltage event should not happen under normal operating conditions.

### Overtemperature Protection

To prevent thermal damage to the LTC3314A, the device incorporates an overtemperature (OT) function. If the die temperature reaches 165°C (typical, not tested), both buck switching regulators will be shut down and remain in shutdown until the die temperature falls to 160°C (typical, not tested).

### Output Voltage Soft-Start

Soft-starting the output limits $V_{IN}$ inrush current and reduces start-up output voltage overshoot. Each buck regulator has an internal voltage ramp that initiates when that regulator is enabled. During soft-start, the output voltage will proportionately track the voltage ramp until it reaches the regulation voltage.

An active pull-down circuit is connected to the internal soft-start node to discharge it in the case of fault conditions. The soft-start ramp will restart when the fault is cleared. Fault conditions that discharge the soft-start voltage ramp are the EN pin transitioning low, $V_{IN}$ voltage falling too low, or thermal shutdown.

### Dropout Operation

As the input supply voltage approaches the output voltage, the duty cycle increases until SW is low for a minimum time of 30ns (typical, not tested). Further reduction of the supply voltage forces the main switch to remain on for more than one cycle, allowing the duty cycle to increase despite the internally set minimum SW low-time. As the input drops further, the main switch stays on for more cycles, until it reaches the maximum allowed 16 cycles. At least one minimum low time is forced every 16 cycles in dropout, limiting the maximum duty cycle to 99% (typical).

Deep in dropout, the output voltage will be approximately determined by 0.99 times the input voltage, minus the voltage drops across the internal high-side MOSFET and the inductor.

### Low Supply Operation

The LTC3314A is designed to operate down to an input supply voltage of 2.25V. One important consideration at low input supply voltages is that the $R_{DS(ON)}$ of the internal power switches increases. Calculate the worst case LTC3314A power dissipation and die junction temperature at the lowest input voltages.

### Output Short-Circuit Protection and Recovery

The peak inductor current level, at which the current comparator shuts off the top power switch, is controlled by the internal $V_C$ voltage. If the output current increases, the error amplifier raises $V_C$ until the average inductor current matches the load current. The LTC3314A clamps the maximum $V_C$ voltage, thereby limiting the peak inductor current.

When the output is shorted to ground, the inductor current decays very slowly when the bottom power switch is on, because the voltage across the inductor is low. To keep the inductor current in control, a secondary limit is imposed on the valley of the inductor current. If the inductor current measured through the bottom power switch is greater than $I_{VALLEYMAX}$ at the end of a cycle, the top power switch will be held off. Subsequent switching cycles will be skipped until the inductor current is reduced below $I_{VALLEYMAX}$.

Recovery from an output short-circuit may involve a soft start cycle if $V_{FB}$ falls more than approximately 100mV below regulation. During such a recovery, $V_{FB}$ will quickly charge up by ~100mV and then follow the soft-start ramp until regulation is reached.

## APPLICATIONS INFORMATION

### Output Voltage and Feedback Network

The output voltage of the buck switching regulators is programmed by a resistor divider between the output and the FB pin. Choose the resistor values according to Equation 1.

$$R_A = R_B\left(\frac{V_{OUT}}{500mV} - 1\right) \quad (1)$$

as shown in Figure 1:

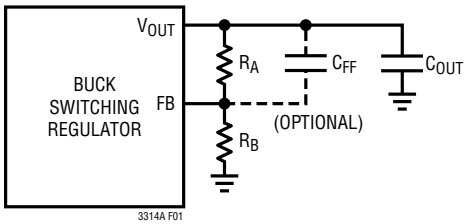



**Figure 1. Feedback Components**

Typical values for $R_B$ range from 40kΩ to 400kΩ. 0.1% resistors are recommended to maintain output voltage accuracy. The buck regulator transient response may improve with an optional phase lead capacitor $C_{FF}$ that helps cancel the pole created by the feedback resistors and the input capacitance of the FB pin. Experimentation with capacitor values between 2pF and 40pF may improve transient response. The values used in the typical application circuits are a good starting point.

### Operating Frequency Selection and Trade-Offs

Selection of the operating frequency is a trade-off between efficiency, component size, transient response, and input voltage range.

The advantage of high frequency operation is that smaller inductor and capacitor values may be used. Higher switching frequencies allow for higher control loop bandwidth and, therefore, faster transient response. The disadvantages of higher switching frequencies are lower efficiency, because of increased switching losses, and a smaller input voltage range, because of minimum switch on-time limitations.

The minimum on-time of the buck regulators imposes a minimum operating duty cycle. The highest switching frequency ($f_{SW(MAX)}$) for a given application can be calculated with Equation 2.

$$f_{SW(MAX)} = \frac{V_{OUT}}{t_{ON(MIN)} \bullet PV_{IN(MAX)}} \quad (2)$$

where $PV_{IN(MAX)}$ is the maximum input voltage, $V_{OUT}$ is the output voltage, and $t_{ON(MIN)}$ is the minimum top switch on-time. This equation shows that a slower switching frequency might be necessary to accommodate a high $V_{IN}/V_{OUT}$ ratio.

The LTC3314A is capable of a maximum duty cycle of 98%. Therefore, the $V_{IN}$-to-$V_{OUT}$ dropout is limited by 0.98 times the input supply, the $R_{DS(ON)}$ of the top switch, the inductor DCR, and the load current.

### Setting the Switching Frequency

The LTC3314A uses a constant frequency, peak current mode control architecture. There are three methods to set the switching frequency. The slope compensation is automatically adapted to the clock frequency.

The first method, connecting the RT pin to $V_{IN}$, sets the switching frequency to the internal default with a nominal value of 2MHz.

The second method is with a resistor ($R_T$) tied from the RT pin to ground. The frequency can be programmed from 1MHz to 3MHz. Table 1 and Equation 3 show the necessary $R_T$ value for a desired switching frequency:

$$R_T = \frac{73.4}{f_{SW}} - 1.9 \quad (3)$$

where $R_T$ is in kΩ and $f_{SW}$ is the desired switching frequency in MHz, ranging from 1MHz to 3MHz.

## APPLICATIONS INFORMATION

**Table 1. $R_T$ Value vs Switching Frequency**

| $f_{SW}$ (MHz) | $R_T$ (kΩ) |
|---|---|
| 1.0 | 71.5 |
| 1.2 | 59.0 |
| 1.4 | 51.1 |
| 1.6 | 44.2 |
| 1.8 | 39.2 |
| 2.0 | 34.8 |
| 2.2 | 31.6 |
| 2.4 | 28.7 |
| 2.6 | 26.1 |
| 2.8 | 24.3 |
| 3.0 | 22.6 |

The third method to set the switching frequency is by synchronizing the internal PLL circuit to an external square wave clock applied to the MODE/SYNC pin. The synchronization frequency range is 1MHz to 3MHz. The square wave amplitude should have valleys that are below 0.4V and peaks above 1.2V. High and low pulse widths should both be at least 40ns.

### Inductor Selection and Maximum Output Current

Considerations in choosing an inductor are inductance, RMS current rating, saturation current rating, DCR, and core loss.

Select the inductor value based on Equation 4 and Equation 5.

$$L \approx \frac{V_{OUT}}{1.2A \bullet f_{SW}} \bullet \left(1 - \frac{V_{OUT}}{PV_{IN(MAX)}}\right) \text{ for } \frac{V_{OUT}}{PV_{IN(MAX)}} \leq 0.5 \quad (4)$$

$$L \approx \frac{0.25 \bullet PV_{IN(MAX)}}{1.2A \bullet f_{SW}} \text{ for } \frac{V_{OUT}}{PV_{IN(MAX)}} > 0.5 \quad (5)$$

where $f_{SW}$ is the switching frequency and $PV_{IN(MAX)}$ is the maximum input voltage.

To avoid overheating of the inductor choose an inductor with an RMS current rating that is greater than the maximum expected output load of the application. Overload and short-circuit conditions may need to be taken into consideration.

In addition, ensure that the saturation current rating (typically labeled $I_{SAT}$) of the inductor is higher than the maximum expected load current plus half the inductor ripple current (Equation 6).

$$I_{SAT} > I_{LOAD(MAX)} + \frac{1}{2}\Delta I_L \quad (6)$$

where $I_{LOAD(MAX)}$ is the maximum output load current for a given application and $\Delta I_L$ is the inductor ripple current calculated by Equation 7.

$$\Delta I_L = \frac{V_{OUT}}{L \bullet f_{SW}} \bullet \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \quad (7)$$

A more conservative choice would be to use an inductor with an $I_{SAT}$ rating higher than the maximum current limit of the LTC3314A.

To keep the efficiency high, choose an inductor with the lowest series resistance (DCR). The core material should be intended for high frequency applications. Table 2 shows recommended inductors from several manufacturers.

# APPLICATIONS INFORMATION

**Table 2. Recommended Inductors with Typical Specifications**

| INDUCTANCE (nH) | $I_{TEMP}$ (A)* | $I_{SAT}$ (A) | DCR (mΩ) | L × W × H (mm) | MANUFACTURER | MANUFACTURER'S PART NUMBER |
|---|---|---|---|---|---|---|
| 220 to 560 | 9.3 to 5.1 | 9.3 to 6.7 | 9.5 to 18.7 | 3.0 × 3.0 × 1.2 | Vishay | IHLP-1212AB-11 |
| 330, 470 | 5.1, 4.9 | 7.6, 6.7 | 19, 23 | 2.5 × 2.0 × 1.2 | Murata | DFE252012F |
| 330 | 4.8 | 6.8 | 21 (Max) | 2.5 × 2.0 × 1.0 | Murata | DFE252010F-R33M |
| 330 | 5.5 | 7.3 | 16 | 2.5 × 2.0 × 1.0 | Cyntec | HMLQ25201T-R33MSR |
| 330 | 5.5 | 8.3 | 14 | 3.0 × 3.0 × 2.0 | Wurth Elektronik | 744383360033 |
| 250 | 5.5 | 12 | 10 | 3.2 × 2.5 × 1.5 | Wurth Elektronik | 74479290125 |
| 240 | 6 | 9.5 | 18 | 2.5 × 2.0 × 1.0 | NIC | R24MTRF |
| 240 | 6.5 | 7.5 | 15 | 2.0 × 1.6 × 1.0 | NIC | R24MTRF |
| 240 | 5 | 6.6 | 19 (Max) | 2.0 × 1.6 × 1.2 | Murata | DFE201612E-R24M |
| 240 | 4.7 | 6.3 | 20 (Max) | 2.0 × 1.6 × 1.0 | Murata | DFE201610E-R24M |
| 220 | 5.9 | 7.0 | 9.4 | 2.5 × 2.0 × 1.0 | Cyntec | HMLB25201T-R22MSR-01 |
| 220 | 7.4 | 7.1 | 8.4 | 2.5 × 2.0 × 1.2 | Vishay | IHHP1008ABERR22M01 |
| 220 | 8.0 | 7.0 | 13 (Max) | 2.5 × 2.0 × 1.2 | XFRMS | XFHCL43LT-R22M |
| 72 to 560 | 23.6 to 8.1 | 16.0 to 6.5 | 2.85 to 21.5 | 3.5 × 3.2 × 1.5 | Coilcraft | XEL3515 |
| 110 | 5.5 | 8.8 | 12 (Max) | 2.0 × 1.2 × 1.0 | Murata | DFE201210S-R11M |
| 100 | 11.13 | 7.38 | 7.31 | 3.3 × 3.3 × 1.0 | Vishay | IHLP1212AZEVR10M5A |
| 100 to 470 | 5.6 to 12 | 5.8 to 10 | 4 to 19 | 2.5 × 2.0 × 1.2 | TDK | TFM252012ALMA |

*Strongly depends on the PCB thermal properties

## APPLICATIONS INFORMATION

### Input Capacitors

Bypass the input of the LTC3314A with at least two ceramic capacitors close to the part, one near each $PV_{IN}$ pin. Connect the ground of each capacitor to a wide PCB trace on the top layer of the PCB that connects to the PGND leads. These capacitors should be 0603 or 0805 in size. Smaller 0201 capacitors can also be placed as close as possible from $PV_{IN1}$ to PGND, and from $PV_{IN2}$ to PGND to reduce input noise with minimal increase in application footprint. See the PCB Layout Considerations section for more detail. X7R or X5R capacitors are recommended for best performance across temperature and input voltage variations (see Table 3). Note that larger input capacitance is required when a lower switching frequency is used. If the input power source has high impedance, or there is significant inductance due to long wires or cables, additional bulk capacitance may be necessary. This can be provided with an electrolytic capacitor.

A ceramic input capacitor combined with trace or cable inductance forms a high quality (underdamped) tank circuit. If the LTC3314A circuit is plugged into a live supply, the input voltage can ring to twice its nominal value, possibly exceeding the LTC3314A's voltage rating. This situation is easily avoided (see Application Note AN88).

**Table 3. Ceramic Capacitor Manufacturers**

| VENDOR | URL |
|---|---|
| Kyocera | www.kyocera-avx.com |
| Murata | www.murata.com |
| TDK | www.tdk.com |
| Taiyo Yuden | www.t-yuden.com |
| Samsung | www.samsungsem.com |
| Wurth Elektronik | www.we-online.com |

### Output Capacitor, Output Ripple and Transient Response

The output capacitor has two essential functions. Along with the inductor, it filters the square wave generated by the LTC3314A to produce the DC output. In this role it determines the output ripple; thus, low impedance at the switching frequency is important. The second function is to store energy in order to satisfy transient loads and stabilize the LTC3314A's control loop.

The LTC3314A is internally compensated and has been designed to operate at a high bandwidth for fast transient response capability. The selection of $C_{OUT}$ will affect the bandwidth of the system, but the transient response is also affected by $V_{OUT}$, $V_{IN}$, $f_{SW}$, and other factors. A good place to start is with the output capacitor value given by Equation 8.

$$C_{OUT} = 20 \bullet \frac{I_{MAX}}{f_{SW}} \sqrt{\frac{0.5}{V_{OUT}}} \quad (8)$$

where $C_{OUT}$ is the recommended output capacitor value in µF, $f_{SW}$ is the switching frequency in MHz, $I_{MAX}$ = 4A per phase is the rated output current in Amps, and $V_{OUT}$ is in Volts.

A lower value of output capacitor can be used to save space and cost, but transient performance will suffer and loop stability must be verified.

Ceramic capacitors have very low equivalent series resistance (ESR) and provide the best output ripple and transient performance. Use X5R or X7R ceramic capacitors (see Table 3). Even better output ripple and transient performance can be achieved by using low-ESL reverse geometry or three-terminal ceramic capacitors.

During a load step, the output capacitor must instantaneously supply the current to support the load until the feedback loop increases the switch current enough to support the load. The time required for the feedback loop to respond is dependent on the compensation components and the output capacitor size. Typically, 3 to 4 cycles are required to respond to a load step, but only in the first cycle does the output drop linearly. Although affected by $V_{OUT}$, $V_{IN}$, $f_{SW}$, $t_{ON(MIN)}$, the equivalent series inductance (ESL) of the output capacitor, and other factors, the output droop, $V_{DROOP}$, is usually about 3 times the linear drop of the first cycle (Equation 9).

$$V_{DROOP} = \frac{3 \bullet \Delta I_{OUT}}{C_{OUT} \bullet f_{SW}} \quad (9)$$

Transient performance and control loop stability can be improved with a higher $C_{OUT}$ and/or the addition of a feedforward capacitor $C_{FF}$ placed between $V_{OUT}$ and FB. Capacitor $C_{FF}$ provides phase lead compensation by

## APPLICATIONS INFORMATION

creating a high frequency zero which improves the phase margin and the high-frequency response. The values used in the typical application circuits are a good starting point. LTpowerCAD® is a useful tool to help optimize $C_{FF}$ and $C_{OUT}$ for a desired transient performance.

Applying a load transient and monitoring the response of the system or using a network analyzer to measure the actual loop response are two ways to experimentally verify transient performance and control loop stability, and to optimize $C_{FF}$ and $C_{OUT}$.

When using the load transient response method to stabilize the control loop, apply an output current pulse of 20% to 100% of full load current having a very fast rise time. This will produce a transient on the output voltage. Monitor $V_{OUT}$ for overshoot or ringing that would indicate a stability problem (see Application Note AN149).

### Output Voltage Sensing

The LTC3314A's AGND pin is the ground reference for the internal analog circuitry, including the bandgap voltage reference. For the single output, 2-phase application, load regulation can be improved by connecting the AGND pin to the negative terminal of the output capacitor ($C_{OUT}$) at the load. Any drop in the high current power ground return path will be compensated. All of the signal components, such as the FB resistor dividers and the $R_T$ resistor, should be referenced to the AGND node. AGND carries very little current and, therefore, can be a minimal size trace.

For dual buck applications, connect the FB resistor dividers, the $R_T$ resistor ground, and the $AV_{IN}$ capacitor ground to the AGND pin close to the part. Connect AGND, using a via, to a low resistance ground plane that minimizes any voltage drops between AGND and the negative terminals of the buck output capacitors.

### Enable Threshold Programming

The LTC3314A has precision threshold enable pins for each buck regulator to enable or disable each buck. When both are forced low, the device enters into a low current shutdown mode.

The rising threshold of both EN comparators is 400mV, with 50mV of hysteresis. The EN pins can be tied to $AV_{IN}$ if the shutdown feature is not used. Adding a resistor divider from $PV_{IN}$ to an EN pin to ground, programs the LTC3314A to regulate that output only when $PV_{IN}$ is above a desired voltage. Typically, this threshold, $PV_{IN(EN)}$ is used in situations where the input supply is current limited or has a relatively high source resistance. A switching regulator draws near constant power from its input source, so source current increases as source voltage drops. This looks like a negative resistance load to the source and can cause the source to current limit or latch low under low source voltage conditions. The $PV_{IN(EN)}$ threshold prevents the regulator from operating at source voltages where problems may occur. Referring to Figure 2, this threshold can be adjusted by setting the values R1 and R2 such that they satisfy Equation 10.

$$PV_{IN(EN)} = \left(\frac{R1}{R2} + 1\right) \bullet 400mV \quad (10)$$

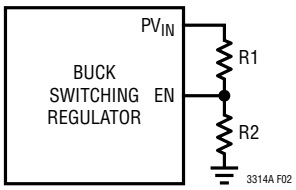



**Figure 2. EN Divider**

The buck regulator will remain off until $PV_{IN}$ is above $PV_{IN(EN)}$. The buck regulator will remain enabled until $PV_{IN}$ falls to 0.875 • $PV_{IN(EN)}$ and EN is 350mV.

Alternatively, a resistor divider from the output of one buck to the EN pin of the second buck provides event-based power-up sequencing, as the first buck reaching regulation enables the second buck. Replace $PV_{IN(EN)}$ in Equation 10 with the desired output voltage of the first buck, (e.g., 90% of the regulated value), at which the second buck is enabled.

# APPLICATIONS INFORMATION

## PCB Layout Considerations

The LTC3314A is a high-performance IC designed for high efficiency and fast transient response. For optimal results carefully consider the layout of the PCB board and follow the recommendations below to ensure proper operation. See Figure 3 for a recommended PCB layout.

1. Connect the PGND pin (Leads C1, C2, C3, D1, D2, D3) directly to a large, unbroken ground plane under the application circuit on the layer closest to the surface layer to minimize thermal and electrical impedance. Additionally, connect the PGND leads to the $PV_{IN1}$ and $P_{VIN2}$ decoupling capacitors on the top layer with short, wide traces.
2. The $PV_{IN1}$ (Leads A1, A2) and $PV_{IN2}$ (Leads F1, F2) input supply leads should have local decoupling capacitors with the ground side of the capacitors connected on the top layer to the ground plane close to the PGND leads. These capacitors provide the AC current to the internal power MOSFETs and their drivers. Large, switched currents flow in these capacitors and it is important to minimize inductance from these capacitors by choosing a small case size, such as 0603, and placing them close to the leads on the top side of the board. To further minimize inductance and input noise, smaller 0201 capacitors can be placed in parallel, also as close as possible to the leads, from $PV_{IN1}$ to PGND and from $PV_{IN2}$ to PGND.
3. Place both regulator inductors on the same side of the board as the LTC3314A. The switching power traces connecting SW1 (Leads A3, B1, B2, B3) and SW2 (Leads E1, E2, E3, F3) to their inductors should be minimized to reduce radiated EMI and parasitic coupling. Due to the large voltage swing on the switching nodes, high impedance sensitive nodes, such as the feedback nodes, should be kept far away or shielded from SW1 and SW2. Minimize the trace lengths from the inductors to their output capacitors.

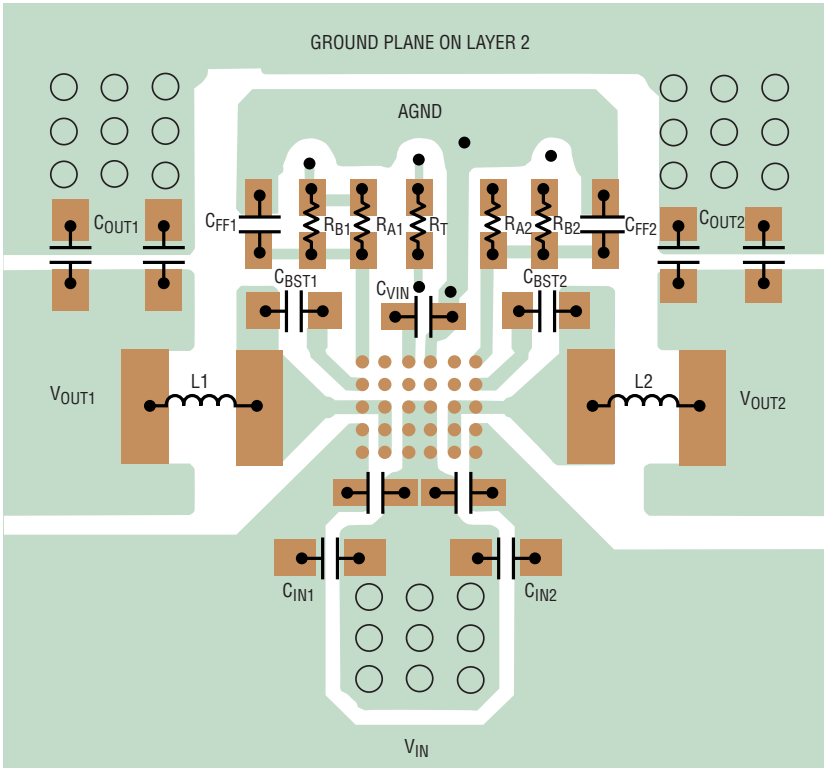



**Figure 3. Recommended PCB Layout**

## APPLICATIONS INFORMATION

4. Connect the ground side of any FB and RT components to AGND (Lead D5). Connect a 1µF decoupling capacitor from $AV_{IN}$ (Lead C5) to AGND, close to the pins. For all layouts, only connect AGND to the rest of the PCB ground plane in one location, to prevent transient currents in the ground plane from also flowing through the AGND trace, which would cause voltage noise between AGND referenced circuits.

   For dual buck applications, connect the AGND pin to the ground plane with a single via, close to the AGND lead. Use an unbroken low resistance ground plane to minimize any voltage drops between AGND and the negative terminals of the output capacitors.

   For 2-phase, single output designs, optionally connect the AGND lead to the negative terminal of the output capacitor ($C_{OUT}$) at the load. This will reduce any load regulation caused by voltage drops between the ground at the load and the LTC3314A voltage reference ground. The AGND node carries very little current and, therefore, can be a minimal size trace. The ground side of any FB and RT components, and the $AV_{IN}$ capacitor ground should connect to the AGND node.

5. Care should be taken in the layout of the PCB to ensure good heat sinking of the LTC3314A. Connect the PGND leads to a large metal area on the top layer. Connect the top layer ground metal to ground plane(s) on lower levels with many thermal vias. These layers will spread heat dissipated by the LTC3314A. The junction temperature, $T_J$, is calculated from the ambient temperature, $T_A$ as given by Equation 11.

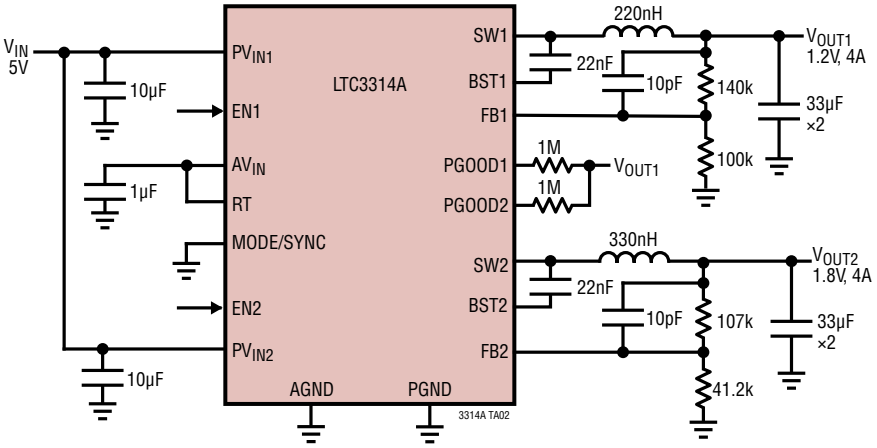
   $$T_J = T_A + (P_D \bullet \theta_{JA}) \quad (11)$$

   Where $\theta_{JA}$ is approximately 58°C/W.

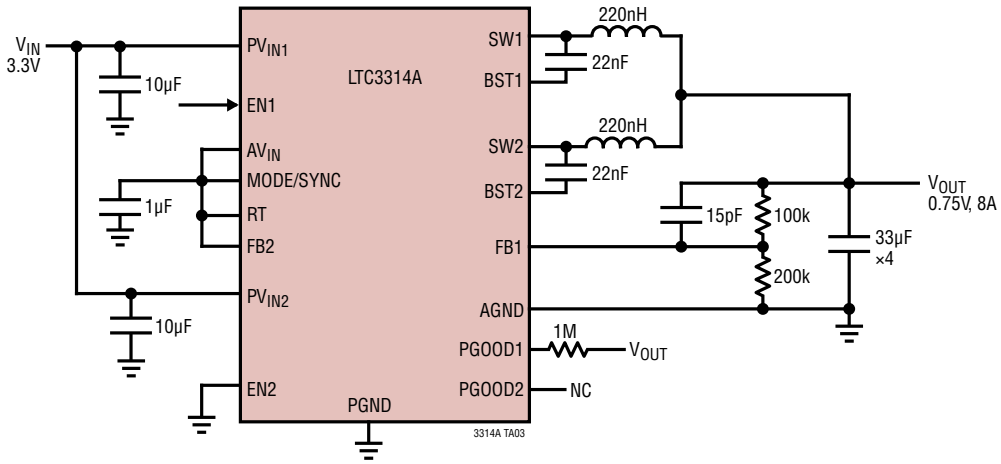
   Power dissipation within the LTC3314A is estimated by calculating the total power loss from an efficiency measurement and subtracting the inductor loss.

# TYPICAL APPLICATIONS

**Dual 1.2V and 1.8V, 2MHz, 4A, $V_{IN}$ = 5V, Pulse-Skipping Mode**

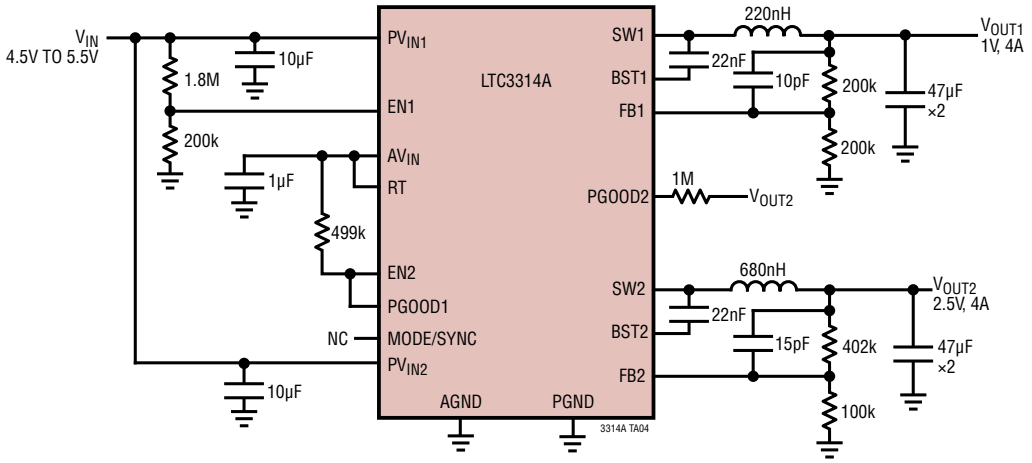



**Single Output 2-Phase, 0.75V, 2MHz, 8A, $V_{IN}$ = 3.3V, Burst Mode Operation**

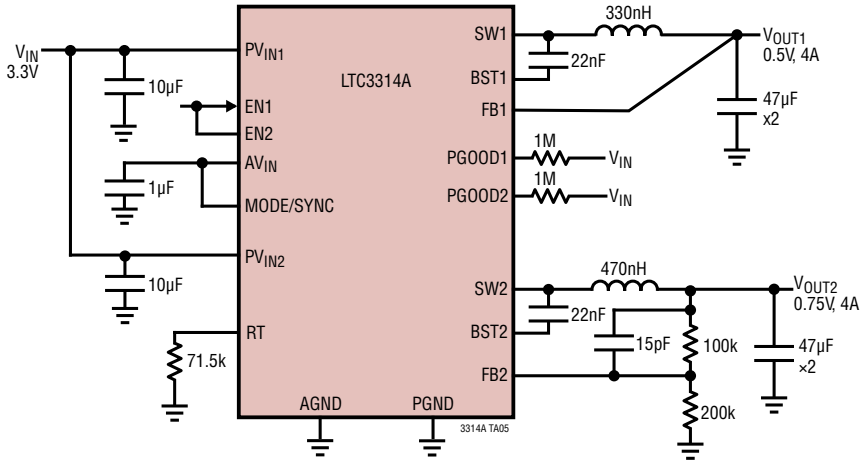


# TYPICAL APPLICATIONS

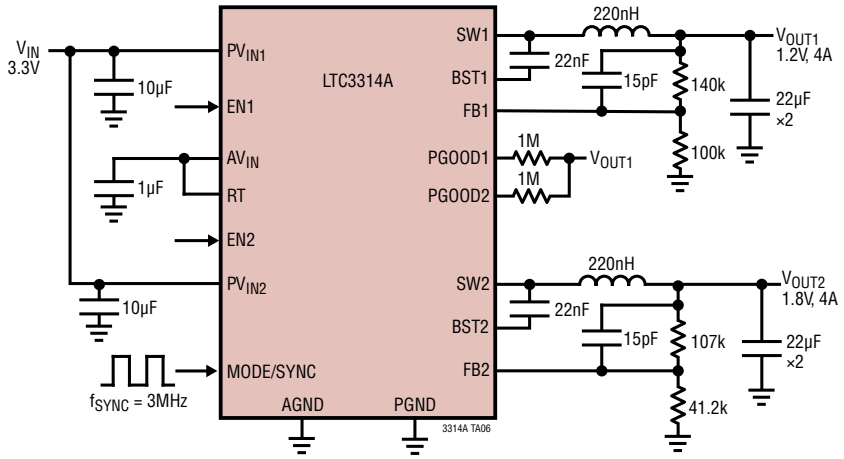
**Dual 1V and 2.5V, 2MHz, 4A, UVLO = 4.0V, Sequential Power-Up Sequencing ($V_{OUT1}$ Powers First), Forced Continuous Mode**




**Dual 0.5V and 0.75V, 1MHz, 4A, $V_{IN}$ = 3.3V, Burst Mode Operation**

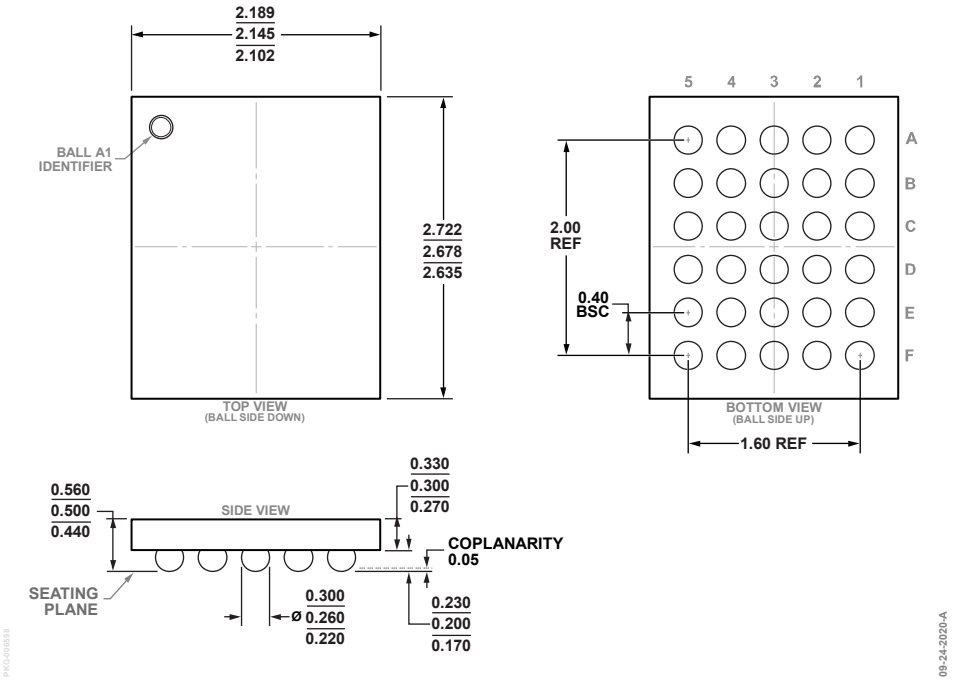



**Dual 1.2V and 1.8V, 3MHz, 4A, $V_{IN}$ = 3.3V, Syncing to 3MHz**



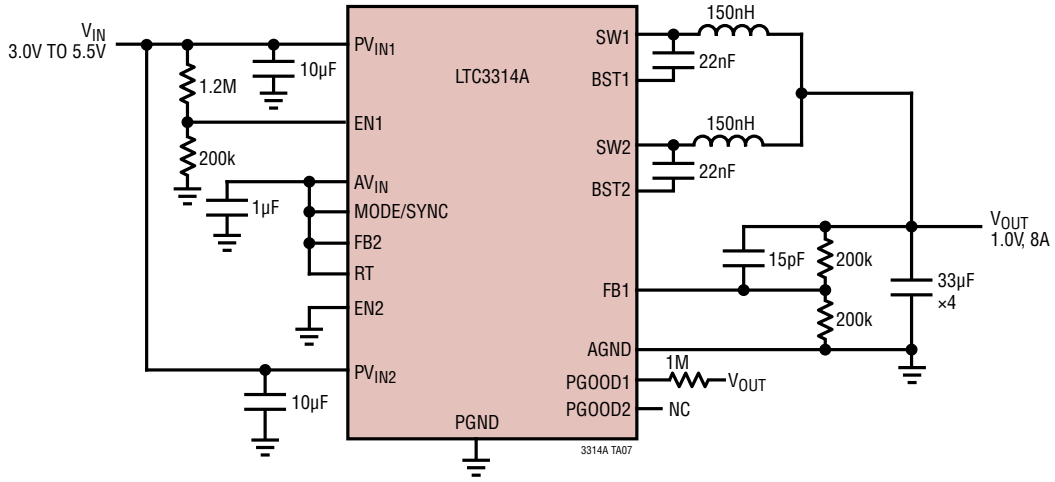
# PACKAGE DESCRIPTION

**WLCSP PACKAGE**
**CB-30-7**
**30-LEAD (2.2mm × 2.7mm × 0.5mm)**



## TYPICAL APPLICATION

**Single Output 2-Phase, 1.0V, 2MHz, 8A, UVLO = 2.8V, Burst Mode Operation**




## RELATED PARTS

| PART NUMBER | DESCRIPTION | COMMENTS |
|---|---|---|
| LTC3312SA | 5V, Dual 6A/Dual-Phase 12A Step-Down DC/DC Regulator | Dual Monolithic Synchronous Step-Down Regulators Each Capable of Supplying 6A at Switching Frequencies Up to 3MHz, Configurable as a Single Output, 2-Phase 12A Buck, 2.25V to 5.5V Input Operating Range, 0.5V to $V_{IN}$ Output Voltage Range with ±1% Accuracy, PGOOD Indication, RT Programming, SYNC Input, Programmable Soft-Start, 4mm × 3mm LQFN |
| LTC3315A/ LTC3315B | Dual 5V, 2A Synchronous Step-Down DC/DCs | Dual Monolithic Synchronous Step-Down Voltage Regulators Each Capable of Supplying 2A at Switching Frequencies Up to 3MHz/10MHz, 2.25V to 5.5V Input Operating Range, 0.5V to $V_{IN}$, Output Voltage Range with ±1% Accuracy, PGOOD Indication, SYNC Input, 2mm × 2mm LQFN |
| LTC3307A/ LTC3307B | 5V, 3A Synchronous Step-Down Silent Switcher® | Monolithic Synchronous Step-Down DC/DC Capable of Supplying 3A at Switching Frequencies Up to 3MHz/10MHz, Silent Switcher Architecture for Ultralow EMI Emissions, 2.25V to 5.5V Input Operating Range, 0.5V to $V_{IN}$ Output Voltage Range with ±1% Accuracy, PGOOD Indication, $R_T$ Programming, SYNC Input, 2mm × 2mm LQFN |
| LTC3308A/ LTC3308B | 5V, 4A Synchronous Step-Down Silent Switcher | Monolithic Synchronous Step-Down DC/DC Capable of Supplying 4A at Switching Frequencies Up to 3MHz/10MHz, Silent Switcher Architecture for Ultralow EMI Emissions, 2.25V to 5.5V Input Operating Range, 0.5V to $V_{IN}$ Output Voltage Range with ±1% Accuracy, PGOOD Indication, $R_T$ Programming, SYNC Input, 2mm × 2mm LQFN |
| LTC3309A/ LTC3309B | 5V, 6A Synchronous Step-Down Silent Switcher | Monolithic Synchronous Step-Down DC/DC Capable of Supplying 6A at Switching Frequencies Up to 3MHz/10MHz, Silent Switcher Architecture for Ultralow EMI Emissions, 2.25V to 5.5V Input Operating Range, 0.5V to $V_{IN}$ Output Voltage Range with ±1% Accuracy, PGOOD Indication, $R_T$ Programming, SYNC Input, 2mm × 2mm LQFN |
| LTC3310/ LTC3310S/ LTC3311/ LTC3311S | 5V, 10A/12.5A Synchronous Step-Down Silent Switcher/Silent Switcher 2 | Monolithic Synchronous Step-Down DC/DC Capable of Supplying 10A/12.5A at Switching Frequencies up to 5MHz, Silent Switcher Architecture for Ultralow EMI Emissions, 2.25V to 5.5V Input Operating Range, 0.5V to $V_{IN}$ Output Voltage Range with ±1% Accuracy, PGOOD Indication, $R_T$ Programming, SYNC Input, Configurable for Paralleling Power Stages, 3mm × 3mm LQFN |
| LTC3616 | 5.5V, 6A 4MHz, Synchronous Step-Down Regulator | 95% Efficiency, $V_{IN}$: 2.25 to 5.5V, $V_{OUT(MIN)}$= 0.8V, $I_Q$ = 64µA, ISD < 1µA, 4mm × 4mm QFN-16 Package |

# Mouser Electronics

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